

EDCON-COMPONENTS



Designed for surface mounting on high density circuit board

Emboss carrier tape packing systems is available for automatic insertion



Technical Informations

| | |
|--|----------------|
| Voltage: | 16Volt |
| Range: | 22µF |
| Dimension; D x L mm | 4x5,4mm |
| Impedance (Ω) max., at 20°C, 100kHz | 3,0Ω |
| Ripple Current (mA rms) at 105°C, 100kHz | 60mA |

| Ordering Code | | | |
|---------------|----------------|-----------|----------|
| 160 | Voltage | | |
| 220 | Range | | |
| D= | A | L= | 0 |

Low Impedance with Operating Temperatur Range of -55°C ~ +105°C
Load Life of 1000~2000hours

| | | |
|-----------------------------|---------------|---|
| Leakage current max. | Ø4 ~ Ø10mm | I = 0,01CV or 3µA whichever is greater (after 2 minutes) |
| | Ø12,5 ~ Ø16mm | I = 0,03CV or 4µA whichever is greater (after 1 minutes) |

Capacitance tolerance ± 20% at 120Hz, 20°C

| | | | | | | | | | | | | | | |
|---|-------|---------------|------|------|------|------|------|------|--|--|--|--|--|--|
| Dissipation factor max. (at 120Hz, 20°C) | WV | | 6,3 | 10 | 16 | 25 | 35 | 50 | | | | | | |
| | Tan δ | Ø4 ~ Ø10mm | 0,22 | 0,19 | 0,16 | 0,14 | 0,12 | 0,12 | | | | | | |
| | | Ø12,5 ~ Ø16mm | 0,26 | 0,22 | 0,18 | 0,16 | 0,14 | 0,12 | | | | | | |

| | | | | | | | | | | | | | | |
|--|---------------|-----------------|-----|----|----|----|----|----|--|--|--|--|--|--|
| Low Temperatur characteristics (Impedance ratio at 120Hz) | WV | | 6,3 | 10 | 16 | 25 | 35 | 50 | | | | | | |
| | Ø4 ~ Ø10mm | Z-25°C / Z+20°C | 2 | 2 | 2 | 2 | 2 | 2 | | | | | | |
| | | Z-55°C / Z+20°C | 5 | 4 | 4 | 3 | 3 | 3 | | | | | | |
| | Ø12,5 ~ Ø16mm | Z-25°C / Z+20°C | 3 | 3 | 2 | 2 | 2 | 2 | | | | | | |
| Z-55°C / Z+20°C | | 10 | 8 | 6 | 4 | 3 | 3 | | | | | | | |

| | | |
|--|--------------------------|-----------------------------------|
| Load Life (after application of the rated voltage for 2000hrs at 105°C | Leakage current | Less than specified value |
| | Capacitance Change | Within ±20% of initial value |
| | Tan δ | Less than 200% of specified value |
| | Ø4 ~ Ø6,3x5,4: 1000hours | |

CHIP Low Impedance 105°C

Part No.: **I15008**

| | | | | | | | | | | |
|-------|--------|------|--------|--------|--------|-----------|-----------|----------|------------|-----------|
| DRW: | Jason | CHKD | Wilson | MATL: | Wilson | TOLERANCE | Mason | DATE | 03.06.2014 | Customer: |
| APPD: | Schumi | | | FINISH | Jamy | | Sheet No. | 2 from 7 | | |

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Shell life (at 105°C) After 1000hours no load test, leakage current, capacitance and tan δ are same as load life value.

| | | |
|-------------------------------------|---|------------------------------------|
| Resistance to soldering heat | After reflow soldering and resistance at room temperature, they meet the characteristics requirements listed at underside | |
| | Leakage current | Less than specified value |
| | Capacitance Change | Within $\pm 10\%$ of initial value |
| | Tan δ | Less than specified value |

| Size | FREQUENCY COEFFICIENT OF PERMISSIBLE RIPPLE CURRENT | | | | | |
|---|---|-----------|-------|-------|------|--------------|
| | Capacitance μF | Frequency | | | | |
| | | 50Hz | 120Hz | 300Hz | 1KHz | 10KHz \leq |
| $\varnothing 4 \sim \varnothing 10\text{mm}$ | 1,0~ 68 | 0,35 | 0,50 | 0,64 | 0,83 | 1,00 |
| | 100~2200 | 0,40 | 0,55 | 0,70 | 0,85 | 1,00 |
| $\varnothing 12,5 \sim \varnothing 16\text{mm}$ | ~680 | 0,45 | 0,65 | 0,80 | 0,90 | 1,00 |
| | 1000 ~4700 | 0,65 | 0,85 | 0,95 | 1,00 | 1,00 |

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| CHIP Low Impedance 105°C | |
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| Customer: | |

| | | | | | | | | | |
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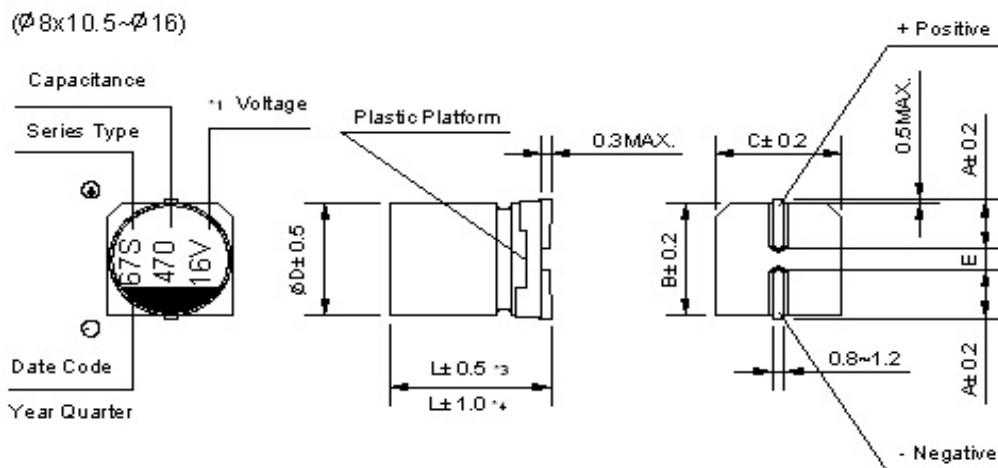
Designed for surface mounting on high density circuit board

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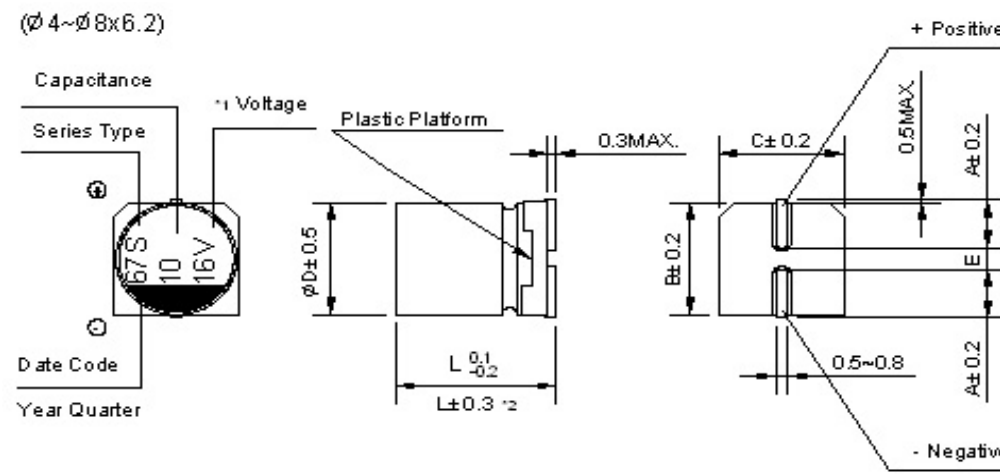


Technical Drawing

Dimension of Size $\varnothing 8 \times 10,5 \sim 16 \text{mm}$



Dimension of Size $\varnothing 4 \sim 8 \times 6,2 \text{mm}$



| D x L | $\varnothing 4 \times 5,4$ | $\varnothing 5 \times 5,4$ | $\varnothing 6,3 \times 5,4$ | $\varnothing 6,3 \times 7,7$ | $\varnothing 8 \times 6,2$ | $\varnothing 8 \times 10,5$ | $\varnothing 10 \times 10,5$ | $\varnothing 10 \times 13,5$ | $\varnothing 12,5 \times 13,5$ | $\varnothing 12,5 \times 16$ | $\varnothing 16 \times 16,5$ |
|----------|----------------------------|----------------------------|------------------------------|------------------------------|----------------------------|-----------------------------|------------------------------|------------------------------|--------------------------------|------------------------------|------------------------------|
| A | 2,0 | 2,2 | 2,6 | 2,6 | 3,4 | 3,0 | 3,3 | 3,3 | 4,9 | 4,9 | 5,8 |
| B | 4,3 | 5,3 | 6,6 | 6,6 | 8,4 | 8,4 | 10,4 | 10,4 | 13,0 | 13,0 | 17,0 |
| C | 4,3 | 5,3 | 6,6 | 6,6 | 8,4 | 8,4 | 10,4 | 10,4 | 13,0 | 13,0 | 17,0 |
| E +/-0.2 | 1,0 | 1,3 | 1,9 | 1,9 | 2,3 | 3,1 | 4,7 | 4,7 | 4,7 | 4,7 | 6,4 |
| L | 5,4 | 5,4 | 5,4 | 7,7 | 6,2 | 10,5 | 10,5 | 13,5 | 13,5 | 16,0 | 16,5 |

*1 Voltage mark (6V) represents 6,3V for $\varnothing 4 \sim 10 \text{mm}$

*3 (L +/- 0.5) is applicable to $\varnothing 8 \times 10,5 \sim \varnothing 10 \text{mm}$

*2 (L +/- 0.3) is applicable to $\varnothing 6,3 \sim 7,7$ and $\varnothing 8 + 6,2 \text{mm}$

*4 (L +/- 1.0) is applicable to $\varnothing 12,5 \sim \varnothing 16 \text{mm}$

RE. Date code and seriew type -1st digit for Year 2nd digit for Quarter, 4 quarter codes in one year area 1,4,7,0

3rd character for Serie S

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| | | | | | | | | | | |
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| APPD: | Schumi | | | FINISH | Jamy | | Sheet No. | 4 from 7 | | |

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Ordering Informations

| Serie | Voltage Code | Tolerance Code | Range Code | Size Code D | Size Code L | Special function | ROHS | Packing Code | | |
|-------|--------------|----------------|------------|-------------|-------------|------------------|------|--------------|--|--|
|-------|--------------|----------------|------------|-------------|-------------|------------------|------|--------------|--|--|

| | | | | | | | | | | |
|---------------|------------|----------|------------|----------|----------|-----------|----------|-----------|--|--|
| I15008 | 160 | M | 220 | A | 0 | XX | R | TR | | |
|---------------|------------|----------|------------|----------|----------|-----------|----------|-----------|--|--|

| | | | | | | | | | |
|--------------|----------------|---------------------|-------------------|-------------------|------------------------|----------------------------|------------------------------|--|--|
| look table | M= ±20% | Ordering Code Range | Look table Code D | Look table Code L | XX= No function | R= ROHS Conform | TR= Tape Reel Packing | | |
| Voltage Code | | | | | | N= NON ROHS Conform | | | |
| | | | | | | | BU= Bulk-Ware | | |
| | | | | | | | | | |

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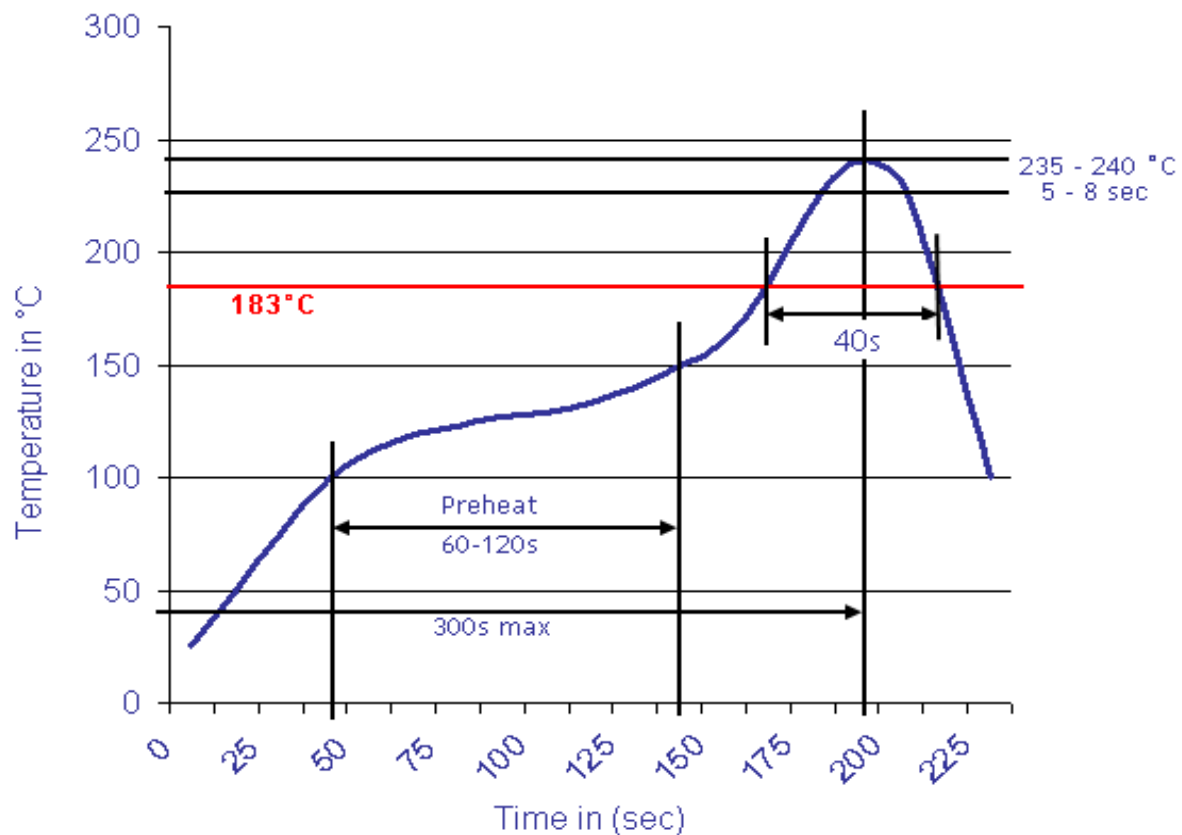
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Soldering Profile Curve

Classification Reflow Profile (JEDEC J-STD-020C)



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